

Issue Date: 3 July 2017

Title of Change:	Update Notice - Cancellation for FPCN21252Z & FPCN21252ZA - Conversion of 14L & 16L SOIC products to Extreme Density Lead Frame (XDLF) assembled at Amkor Technology Philippines P1.
Proposed first ship date:	N/A
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>Koen.Matthijs@onsemi.com</u> >
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < <u>Phine.Guevarra@onsemi.com</u> >.
Type of notification:	ON Semiconductor will consider this cancellation of change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change category:	□ Wafer Fab Change
Change Sub-Category(s): □ Datasheet/Product Doc change □ Datasheet/Product Doc change □ Shipping/Packaging/Marking □ Manufacturing Process Change □ Product specific change □ Other:	
Sites Affected:	plicable ON Semiconductor site(s): I External Foundry/Subcon site(s) Amkor Technology Philippines P1
Description and Purpose:	
The conversion at Amkor Technology Philippines P1, a dual assembly house, of 14L & 16L SOIC products to Extreme Density Lead Frame (XDLF) is cancelled.	
List of affected Standard Parts	
AMIS41683CANN1RG NCV7420D23R2G NCV7420D25R2G	